

HBS602 THRU HBS610

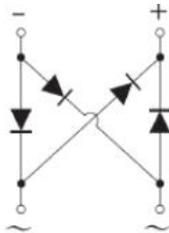
Glass Passivated Single-Phase 6.0Amp Surface Mount Bridge Rectifier



Features

- Surface mount bridge, small package;
- Ideal for printed circuit boards;
- Glass passivated chip junction;
- High surge current capability;
- High heat dissipation capability;
- Low profile package;
- Low forward voltage drop;
- Plastic package has Underwrites Laboratory Flammability Classification 94V-0
- This is a Pb - Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: HBS;
- Epoxy meets UL-94V-0 Flammability rating;
- Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102;
- High temperature soldering guaranteed: Solder Reflow 260°C, 10seconds;
- Polarity: As marked on body;
- Marking: Type number;

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase half wave 60Hz, resistive or inductive load. For capacitive load current derate by 20%.

Type Number	Symbol	HBS602	HBS604	HBS606	HBS608	HBS610	Units	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{DC}	200	400	600	800	1000	V	
RMS Reverse Voltage	V _{RMS}	140	280	420	560	700	V	
Maximum average forward rectified output current at @T _A =25°C	I _(AV)	6						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	170						A
Rating for fusing (t<8.3ms)	I ² t	120						A ² sec

FIG.3 Maximum Non-Repetitive Peak Forward Surge Current per Diode

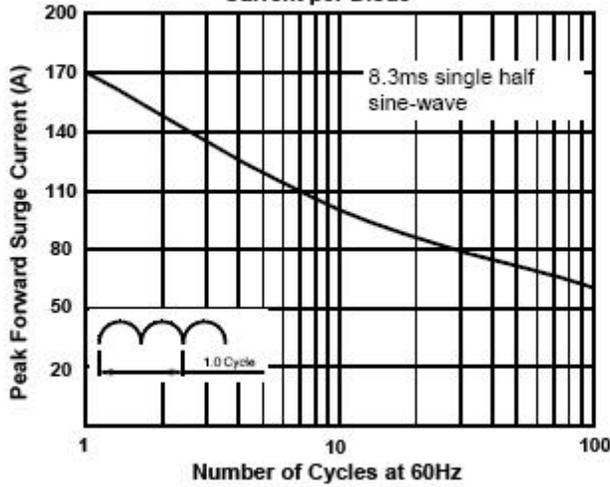


FIG.4 Typical Reverse Characteristics per Diode

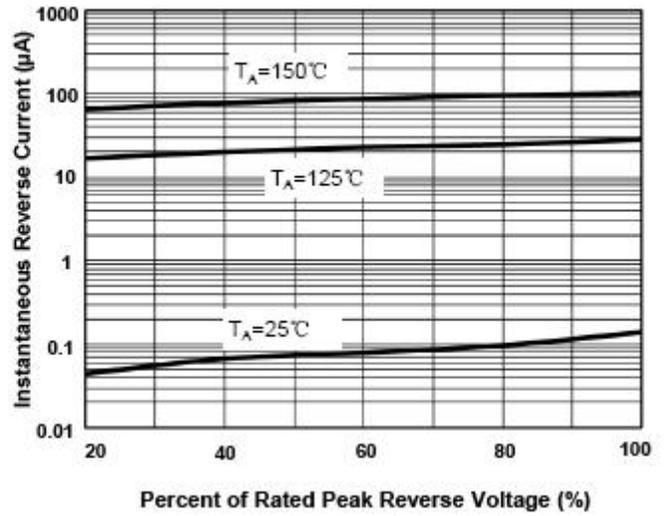
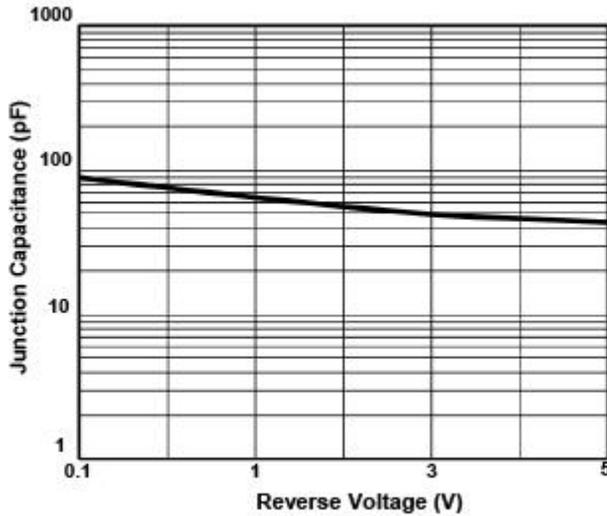
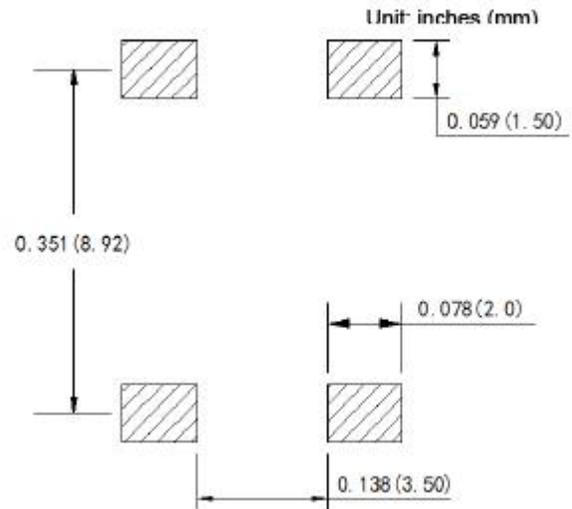


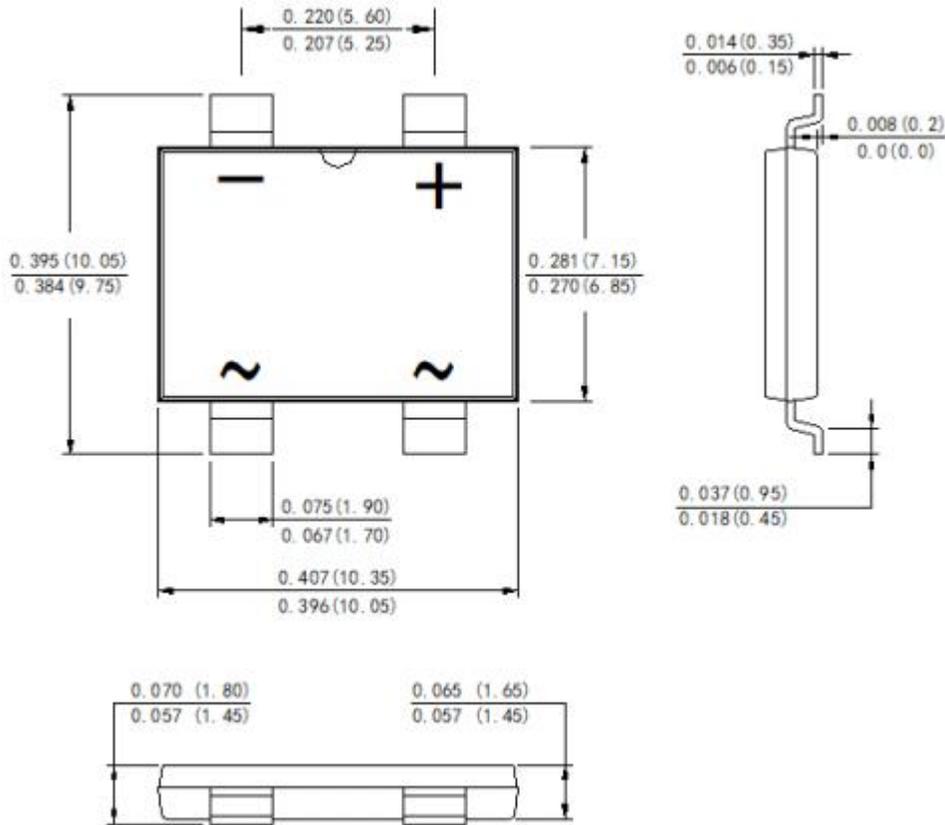
FIG.5 Typical Junction Capacitance per Diode



Suggested PCB printfoot layout



Mechanical Dimensions HBS(Inches/Millimeters)

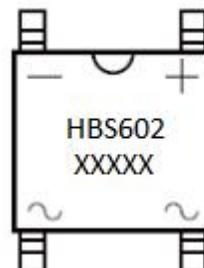


Ordering Information

Device	Package	Plating	Shipping
HBS602 THRU HBS610	HBS (Pb-Free)	Pure Sn	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



Where XXXXX is YYWWL

HBS602 = Type Number
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

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